



Ansys Releases On-Demand Content From Its IDEAS Digital Forum

October 1, 2020

Inaugural event featured keynotes from semiconductor industry influencers and decision makers

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IDEAS_Digital_Forum

Key Highlights

- Ansys hosted its first virtual event dedicated to semiconductor designers and decision makers
- Keynote speakers included industry leaders Nvidia, Arm, Google, Broadcom, Intel, Qualcomm, MediaTek, STMicroelectronics, Ericsson, Samsung, TSMC and more

Content from [Ansys'](#) (NASDAQ: ANSS) inaugural Innovative Designs Enabled by Ansys Semiconductors (IDEAS) Digital Forum is now available for [on-demand viewing](#). The two-day global event featured thought leadership keynotes and presentations from industry leaders at Arm, TSMC, Ericsson and more, along with technology sessions and product updates.

IDEAS Digital Forum content explored the importance of simulation to analyze and optimize integrated circuit (IC) power, performance and reliability. Keynote and workshop speakers discussed how using high fidelity analysis solutions save designers time and increase efficiency through better estimations early in the design process.

The forum served as a hotbed for technical insights into how multiphysics is used to verify foundry sign-off for some of the biggest and most advanced chip design projects in the world. With 16 hours of content, the forum featured technical breakout tracks that delved into an array of topics and design styles, such as high-performance computing, high-speed analog, 2.5D/3D-IC packaging, power integrity, and low-power register-transfer level analysis.

IDEAS also featured two roundtable panel discussions. A technical discussion, titled "Beyond Moore," explored the duality of Moore's Law and newer techniques. The second panel discussion, "Women In Technology Accelerating Diversity and Inclusion," focused on the topic of diversity in the high-tech industry.

"Multiphysics analysis has become a pervasive requirement for advanced semiconductor designs," said John Lee, general manager and vice president at Ansys. "Ansys simulation is at the forefront of semiconductor enablement for the most cutting-edge technology, whether that's artificial intelligence and machine learning, high-performance computing, 5G or autonomous vehicles. The number of attendees and incredible speaker lineup are a testament to the power and value of Ansys solutions."

About Ansys

If you've ever seen a rocket launch, flown on an airplane, driven a car, used a computer, touched a mobile device, crossed a bridge or put on wearable technology, chances are you've used a product where Ansys software played a critical role in its creation. Ansys is the global leader in engineering simulation. Through our strategy of Pervasive Engineering Simulation, we help the world's most innovative companies deliver radically better products to their customers. By offering the best and broadest portfolio of engineering simulation software, we help them solve the most complex design challenges and create products limited only by imagination. Founded in 1970, Ansys is headquartered south of Pittsburgh, Pennsylvania, U.S.A. Visit www.ansys.com for more information.

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